

## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		ADG/21/12659
1.3 Title of PCN		L9906TR, L9906CTR, L9907TR (UQ29): High Density Leadframe Introduction
1.4 Product Category		see list
1.5 Issue date		2021-03-09

### 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio GALLINARI
2.1.2 Marketing Manager	Massimo BARNI
2.1.3 Quality Manager	Alberto BIGNAZZI

### 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	ST Muar (Malaysia)

### 4. Description of change

	Old	New
4.1 Description	Standard Leadframe	High Density Leadframe
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

### 5. Reason / motivation for change

5.1 Motivation	Capacity Increase
5.2 Customer Benefit	CAPACITY INCREASE

### 6. Marking of parts / traceability of change

6.1 Description	Internal traceability
-----------------	-----------------------

### 7. Timing / schedule

7.1 Date of qualification results	2021-03-03
7.2 Intended start of delivery	2021-04-30
7.3 Qualification sample available?	Upon Request

### 8. Qualification / Validation

8.1 Description	12659 Validation.pdf	
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date 2021-03-09

### 9. Attachments (additional documentations)

12659 Public product.pdf  
12659 Validation.pdf  
12659 Details.pdf

<b>10. Affected parts</b>		
<b>10.1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
	L9907	
	L9907TR	

**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

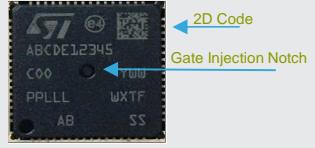
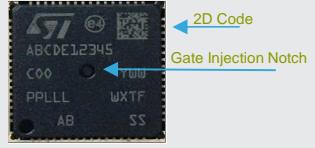
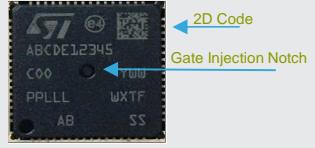
Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved

## PRODUCT/PROCESS CHANGE NOTIFICATION

<b>TITLE</b>	L9906TR, L9906CTR, L9907TR (UQ29): High Density Leadframe Introduction																		
<b>IMPACTED PRODUCTS</b>	<p>Below Products Housed in TQFP-64 10x10 EP :</p> <ul style="list-style-type: none"> <li>✚ L9906TR</li> <li>✚ L9906CTR</li> <li>✚ L9907TR</li> </ul>																		
<b>MANUFAC. STEP</b>	Assembly																		
<b>INVOLVED PLANT</b>	ST Muar Plant (Malaysia)																		
<b>CHANGE REASON</b>	Capacity Increase																		
<b>CHANGE DESCRIPTION</b>	<p>Introduction of High Density Leadframe:</p> <table border="1" data-bbox="518 1178 1339 1875"> <thead> <tr> <th>Item</th> <th>Before</th> <th>After</th> </tr> </thead> <tbody> <tr> <td>Strip size</td> <td>57 x 215mm</td> <td>70 x 250mm</td> </tr> <tr> <td>Density (qty/strip)</td> <td>30 units</td> <td>64 units (HD)</td> </tr> <tr> <td>Mold gate Injection</td> <td>Side gate</td> <td>Centre top gate</td> </tr> <tr> <td></td> <td>No</td> <td>Yes</td> </tr> <tr> <td>2D Marking</td> <td>  </td> <td>  </td> </tr> </tbody> </table> <p>No change in Bill Of Material (LF Finishing, Die Attach, Wire, Resin)</p>	Item	Before	After	Strip size	57 x 215mm	70 x 250mm	Density (qty/strip)	30 units	64 units (HD)	Mold gate Injection	Side gate	Centre top gate		No	Yes	2D Marking		
Item	Before	After																	
Strip size	57 x 215mm	70 x 250mm																	
Density (qty/strip)	30 units	64 units (HD)																	
Mold gate Injection	Side gate	Centre top gate																	
	No	Yes																	
2D Marking																			

<b>TRACEABILITY</b>	Internal Traceability
<b>VALIDATION</b>	According to ZVEI Delta Qualification Matrix here below changes selected: <ul style="list-style-type: none"><li>• SEM-PA-13</li><li>• SEM-PA-14</li><li>• SEM-EQ-02</li></ul>
<b>REPORTS</b>	Validation result of new lead frame and additional details included 12659 Validationom.pdf



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** L9906TR, L9906CTR, L9907TR (UQ29): High Density Leadframe Introduction

**PCN Reference :** ADG/21/12659

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

L9907	L9907TR	
-------	---------	--



### **IMPORTANT NOTICE – PLEASE READ CAREFULLY**

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved



# UQ29 (L9906TR / L9906CTR / L9907TR) TQFP10x10 64L EP in Muar Migration to HD Line



ST Restricted

# Change Description

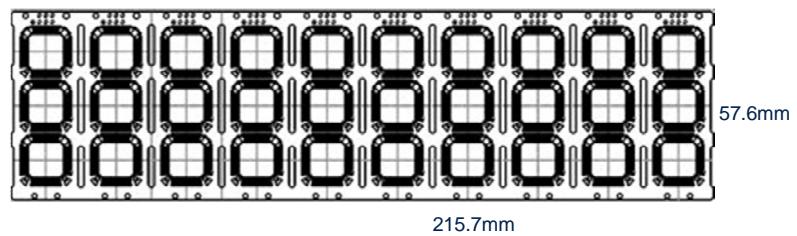
- As part of the overall strategy for QFP14x14, QFP10x10 and QFP7x7, we are progressing with the migration of UQ29 from current matrix line to High Density (HD) line in Muar Assy Plant
- Element of Changes for UQ29 in TQFP10x10 64L EP

## Bill of Material

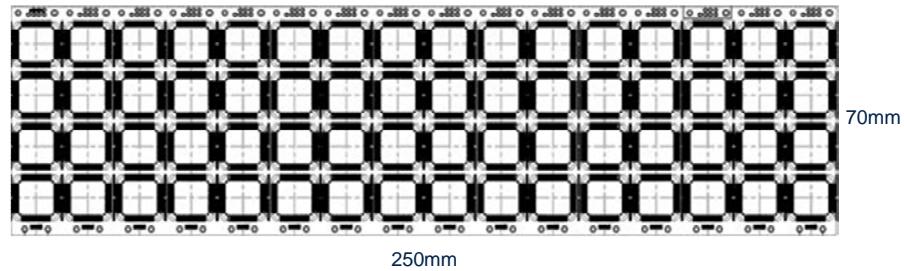
Item	Before	After
Strip size	57 x 215mm	70 x 250mm
Density (qty/strip)	30 units	64 units (HD)
LF Finishing	RTUPG	RTUPG
Die Attach Material	2C2	2C2
Wire	Au	Au
Resin	G700LS	G700LS
Mold gate Injection	Side gate	Centre top gate
2D Marking	No	Yes

# Strip size comparison

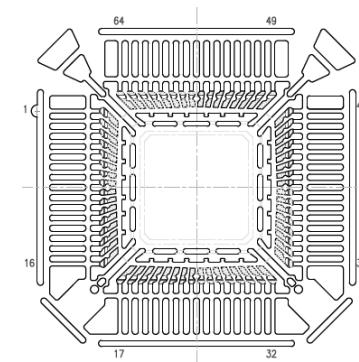
Matrix  
3x10  
30 units



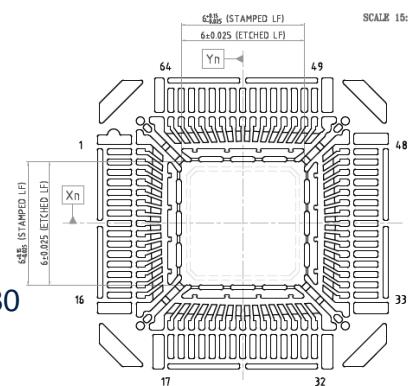
HD  
4x16  
64 units



Matrix  
UQ29 :  
5FT97454

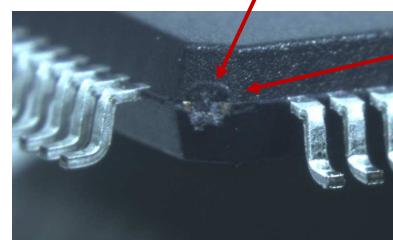
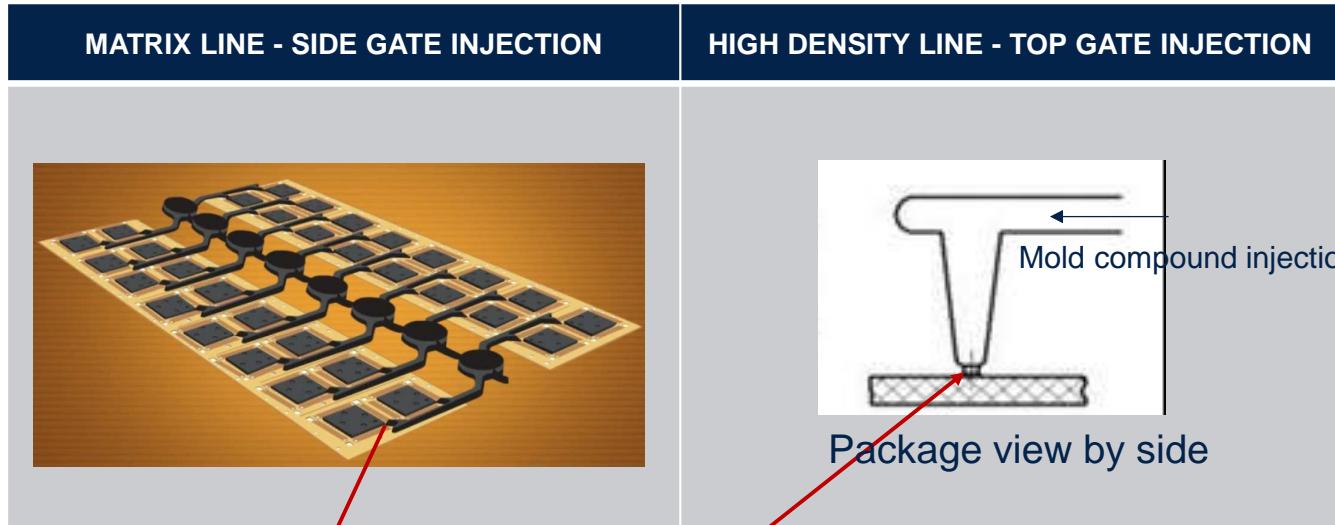


Matrix  
UQ29 :  
5FT00180



# Mold Injection Gates

Same Basic Technology - Transfer Molding



Gate Injection Notch

**Wire sweeping reduction  
with Top Central Gate**

# Marking Composition comparison

Current Matrix Line



New HD Line



# ZVEI ID Selection

PROCESS - ASSEMBLY		
X	SEM-PA-13	Change of product marking
X	SEM-PA-14	Change in process technology (e.g. trim and form, leadframe preparation ...)
EQUIPMENT		
X	SEM-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.

- 2D Marking introduction and central top notch
- HD strip leadframe introduction
- New Equipment, but same basic technology  
transfer molding

With the above selection, ZVEI recommends to perform:

- ✓ Solderability tests → Done by ST
- ❖ Electrical Distribution Comparison (3T) → Meaningless for such change

# ST Qualification Plan

No	Test Name	Test method	Test Condition/S.S per Lot/# Lots	Steps	#Lots / comments	Sample size		
						Qual 1 (LL)	Qual 2 (NN)	Qual 3 (HH)
1	PC (MSL3)	JEDEC J-STD-020	Peak Reflow Temp = 260°C	Final	MSL 3 will be applied on all the parts submitted to TC & AC	159	159	159
2	TC Thermal Cycle	JESD22-A104	-55°C/+150°C ATE	500 cycles	Delamination check (SAM) for all Unit  DPA @ 500TC & 1000TC: Wire Bond Pull/ Wire Stitch Pull/Ball Bond Shear on 5 parts each lot	82	82	82
				1000 cycles		82	82	82
3	AC Autoclave	JESD22-A102	2atm, 121°C ATE	96hrs	Delamination check (SAM) for all Unit	77	77	77
4	HTS High Temperature Storage	JESD22-A103	150°C (without bias) ATE	500hrs	Delamination check (SAM) for all Unit  Read point after 500hr & 1000hr. DPA @ 500hr & 10000hr Wire Bond Pull/ Wire Stitch Pull/Ball Bond Shear on 5 parts each lot	82	82	82
				1000hrs		77	77	77

Qual lot	Raw Line Code	CP	Lot#	Wire Bonding Parameters
Qual 1 (LL)	HA9I*UQ29CB1	L9906CTR	990380AN01	Low Force, Low Energy
Qual 2 (NN)	HA9I*UQ29CC1	L9906TR	990371MK01	Nominal Force, Nominal Energy
Qual 3 (HH)	HA9I*UQ29CB1	L9906CTR	990380AN02	High Force, High Energy



# **HA9I\*UQ29CB1/CC1**

## **HD Conversion : TQFP 10x10 64L EP**

### **Reliability Summary**

Updated : 09 February 2024  
Prepared By : René STEPHAN Reliability Laboratory



ST Restricted

## UQ29 – EP HD Conversion

Note: Sampling 159 pcs/lot – taken from tested good units after FT.

Reliability Test Status									
No	Test Name	Pre c	Condition/ Method	Steps	Steps	Fails/SS			
						990380AN01 HA9I*UQ29CB1 (LL)	990371MK01 HA9I*UQ29CC1 (NN)	990380AN02 HA9I*UQ29CB1 (HH)	
1	PC (JL3 STD)		Bake 24 hrs @ 125°C Soak 192 hrs @ 30°C / 60% RH Reflow Profile = J-STD-020D (Tmax = 260°C)	Final	TSAM (0hr)	0 delam / 60 pcs	0 delam / 60 pcs	0 delam / 60 pcs	
					CSAM TOP (0hr)	0 delam / 60 pcs	0 delam / 60 pcs	0 delam / 60 pcs	
					ATE	0 def / 159 pcs	0 def / 159 pcs	0 def / 159 pcs	
					TSAM	0 delam / 40 pcs	0 delam / 40 pcs	0 delam / 40 pcs	
					CSAM TOP	0 delam / 40 pcs	0 delam / 40 pcs	0 delam / 40 pcs	
2	TC	Yes	TA = -55°C / +150°C	500 Cycle	ATE	0 def / 82 pcs	0 def / 82 pcs	0 def / 82 pcs	
					TSAM	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	
					CSAM TOP	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	
					WPT & BS	Pass	Pass	Pass	
				1000 Cycle	ATE	0 def / 77 pcs	0 def / 77 pcs	0 def / 77 pcs	
					TSAM	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	
					CSAM TOP	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	
					WPT & BS	Pass	Pass	Pass	
3	PPT	Yes	TA = PPT 121°C/ 2Atm	96 hrs	ATE	0 def / 77 pcs	0 def / 77 pcs	0 def / 77 pcs	
					TSAM	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	
					CSAM TOP	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	

## UQ29 – EP HD Conversion

Note: Sampling 159 pcs/lot – taken from tested good units after FT.

Reliability Test Status									
No	Test Name	Pre c	Condition/ Method	Steps	Steps	Fails/SS			
						990380AN01 HA9I*UQ29CB1 (LL)	990371MK01 HA9I*UQ29CC1 (NN)	990380AN02 HA9I*UQ29CB1 (HH)	
4	HTS	No	TA = 150°C	500 hrs	ATE	0 def / 82 pcs	0 def / 82 pcs	0 def / 82 pcs	
					TSAM	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	
					CSAM TOP	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	
					WPT & BS	Pass	Pass	Pass	
				1000 hrs	ATE	0 def / 77 pcs	0 def / 77 pcs	0 def / 77 pcs	
					TSAM	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	
					CSAM TOP	0 delam / 20 pcs	0 delam / 20 pcs	0 delam / 20 pcs	
					WPT & BS	Pass	Pass	Pass	